

ABSTRACT

With a surface mount SAW device constituted so that an outer surface of a SAW chip is covered with a heated and softened sheet resin, a resin is filled into skirts of the SAW chip, and so that an airtight space is thereby formed below IDT electrode on a lower surface of the SAW chip, it is possible to dispense with negative pressure suction from through holes formed in a mounting substrate so as to ensure a filling amount of the resin into gaps, and dispense with strict management of heating temperature and suction profiles. A flip-chip mounting step of mounting the SAW chip on the mounting substrate by flip-chip bonding, a lamination step of pressurizing a resin sheet while softening or melting the resin sheet from one end of the mounting substrate toward the other end of the mounting substrate, thereby covering the outer surface of the SAW chip with the resin while securing the airtight space, a press molding step of pressurizing and heating the SAW chip, thereby hardening the resin while suppressing expansion of a gas within the airtight space, and a post-hardening step of heating a SAW device which has been subjected to the press molding step at a temperature and at a time at which the resin is completely hardened, are provided, and a thickness t_r of the resin sheet before the lamination step has a relationship of $L/[(X+G_x)(Y+G_y)] \leq t_r$.